

Q-SMEC (Quantum-Superconducting Magnetic Energy Containment) Materials Taxonomy Scientific Foundations

1) Q-SMEC Quantum Physics Modeling and Materials:

A) Physics Based Quantum Neural Network (PBQNN) model of a parameterized Quantum Circuit with:

- i) Minimum 10, optimal 100+ qubits
- ii) Brick layer ansatz circuit with 100+ entanglement layers
- iii) Single qubit rotation layer approach
- iv) Hybrid optimizer

Q-SMEC utilizes varying quantities of up to 22 constituent elements (including Germanium, Gallium, Antimony, Tellurium, Selenium, Aluminum, Niobium, Nitrogen, Tin, Titanium, and eleven undisclosed elements)

The PBQNN Circuit model uses additional physics engines to optimize localized quantum field containment in picostructure lattice geometry

- Hilbert Space Density Matrix Functional Theory
- Coupled Wave Function
- Born-Infeld Electrodynamics Entropy Optimization
- Dirac Plasmon Polariton Metamaterials with quantum bonds ("bondons) optimizing plasmon quantum tunneling (equivalent to 100 trillion mechanical bonds per square centimeter)
- Effective Hamiltonian $H = H_{\text{band}} + H_{\text{defect}} + H_{\text{coupling}} + H_{\text{field}}$.
- Transport modeled via semiclassical Boltzmann or Kubo-Greenwood

Q-SMEC PBQNN is resident on secure vault server, with access to IBM Starling

CII NIKET North America LLC PROPRIETARY

B) Classical AI optimized Design of Experiments (DOE) systems are trained on material parameter–performance datasets, to determine optimal segmented heterostructures (local Q-field intensity gradients) for frequency tuning.

Success Criteria:

- Demonstrable $\geq 10 \times$ sensitivity and $\geq 10 \times -100 \times$ SNR improvement at lowest SWaP-C
- Cyber/Physical Security-by-Design: Obfuscated layer ordering, sacrificial signature films, active tamper sense, PUF anchors tied to control firmware.
- Aligned with results from US DOE National Labs (Brookhaven, Argonne, Oak Ridge, Berkeley, Fermi) and DARPA Programs (RQS PNT, ADAPT, IST etc)

2) Q-SMEC Sensor Manufacturing Modalities

- **Thin Film:** Atomic Layer Deposition (ALD), Chemical Vapor Deposition (CVD), or sputtering techniques are employed

Fabrication Process Windows (Initial)

Process	Temp (°C)	Pressure	Other Parameters	Targets
ALD	120–350	10–500 mTorr	growth 0.8–1.5 Å/cycle, purge ≥ 2 s	roughness < 0.5 nm RMS per 100 nm
PVD Sputter		1–10 mTorr Ar/N ₂	200–600 W, rate 0.5 -- 5 nm/s, substrate bias –20...–150 V	
CVD	300–800		precursor-specific	stoichiometry error $\leq \pm 2\%$
Anneal	250–800		30–120 min, forming gas/vacuum	crystallinity XRD FWHM \leq baseline $\times 0.6$
Nanoimprint	120–200		pressure 20–50 bar	CD ≤ 50 nm, LER ≤ 3 nm

- **Pico/Nano 3D-Printing** using Stratasys-equivalent systems

3) Q-SMEC Test and Measurement Protocols

- **Electrical:** Impedance and noise spectra
- **Optical:** Responsivity, bandwidth, and gain linearity
- **Structural:** X-ray Diffraction (XRD), Transmission Electron Microscopy (TEM), and Secondary Ion Mass Spectrometry (SIMS)

4) Q-SMEC Use Case Non-Recurring Engineering Project Plan and Technology and Manufacturing Readiness Level (TRL/MRL) Path

Each Use Case Instantiation adheres to a six-task Project Plan:

Task	Description	NTE Weeks	NTE \$	TRL/MRL
1	Optimized Sensor Physics Quantum Modeling	8	\$100K	3
2	Optimized AI Design of Experiments (Modeling)	8	\$110K	4
3	Sensor Prototype Fabrication	12	\$190K	5/6
4	Beta Testing	10	\$110K	7
5	Low-Rate Initial Production	8	\$130K	8
6	Device Integration/Full Rate Production	8	\$130K	9

5) Q-SMEC Intellectual Property (IP) and Licensing Architecture

- **Model:** Exclusive and non-exclusive licenses are offered, differentiated by field-of-use and geography.
- **Revenue:** Revenue generation is based on an upfront fee complemented by recurring quarterly royalties.
- **Milestones:** Licenses become available upon the completion of Task 2.
- **Co-IP Option:** Investors providing early-stage funding receive proportional ownership of intellectual property.

6) Q-SMEC PATHFINDER PROJECTS 1-6:

PROJECT 1: TERAHERTZ SENSOR/EMITTER

Major Use Cases:

- National Security and Commercial High Speed Wireless Communications
- Health Care Imaging
- Materials Spectroscopy

Q-SMEC Physics Parameter Optimization Values Targets:

Parameter	Value
Noise Equivalent Power (NEP)	0.01-1 pW/sqr Hz
Highest Signal to Noise Ratio (SNR)	100-140 dB Peak
Q-Factor	Greater than 1000
Figure of Merit (FOM)	Greater than 2500
Frequency Range	0.1 to 10 THz
Dynamic Range	Higher than 110 dB
Response Time	Less than 150 picoseconds
Subwavelength Resolution	150 nanometers

CII NIKET North America LLC PROPRIETARY

PROJECT 2: SOLID-STATE HIGH-ENERGY LASER

Major Use Cases:

- National Security Directed Energy Weapons, ISR/Electronic Attack
- Precision Manufacturing
- Commercial Fusion Energy
- Precision Medical Surgery

Q-SMEC Physics Parameter Optimization Values Targets:

Power	Beam Quality M2	Wavelength Range	Operating Range	Bandwidth	Resolution	Pulsing/Mode
100kW-MW+ feasible	1.1	0.4-1.7-micron, 3–5-micron, 8-14 micron	10 Km+	100 Nm	5-10 Micron	Picosecond Pulse and/or Continuous Wave with adjusted Thermal Management

**PROJECT 3: DEEP UNDERGROUND
EXTRA LOW FREQUENCY SENSOR**

Major Use Cases:

- Commercial Mining (Cu/Ag/Mo, Strategic Minerals) and Oil/Gas Exploration
- National Security Covert Naval Submarine Communications
- National Security Underground Structure Detection

Q-SMEC Physics Parameter Optimization Values Targets:

Parameter	Value
Noise Equivalent Power (NEP)	near elimination of 1/f flicker noise
Highest Signal to Noise Ratio (SNR)	25-35 dB
Q-Factor	1500-15,000
Figure of Merit (FOM)	1-2 pT/sq Hz
Frequency Range	0.01 to 10 Hz
Sensitivity	0.01-0.05 pT/sq Hz
Response Time	50-75 milliseconds

CII NIKET North America LLC PROPRIETARY

PROJECT 4: DATA CENTER ELECTRONICS ENERGY EFFICIENCY OPTIMIZATION

Major Use Cases:

- IT/Servers CPU/GPU and RAM Power Reduction: 40-50%
- HVAC/Chillers/Fans/Pumps Power Reduction: 30%
- UPS/Transformer/PDU Power Reduction: 10%
- Routers/Switches/Firewalls Power Reduction: 5%
- Storage HD/SSD Power Reduction: 5%

Q-SMEC Physics Parameter Optimization Values Targets

- Matrix Diffusion Channel Size
- Conductivity
- Strain Elimination/Minimization
- Redox Voltage
- Interface Coating

CII NIKET North America LLC PROPRIETARY

PROJECT 5: VLCLO RCS (RADAR CROSS SECTION) STEALTH MATERIAL

Major Use Cases:

- National Security Reduced Detection Range and Increased Countermeasures Effectiveness
- Commercial Airport Signal Interference Control
- Commercial Antenna Shielding

Q-SMEC Physics Parameter Optimization Values Targets:

Property	Value
Impedance Matching	
Complex Permittivity: Imaginary Component	0.1
Complex Permeability: Imaginary Component	0.1
High Dielectric/Magnetic Loss	over Wide Bandwidth
Lightweight	0.01 g/sq cm
Layer Thickness	50 microns

CII NIKET North America LLC PROPRIETARY

PROJECT 6: S/X-BAND SENSOR/EMITTER

Major Use Cases:

- National Security Long-Range, All-Weather Surveillance, Marine Navigation
- National Security and Commercial Space Satellite Communications

Q-SMEC Physics Parameter Optimization Values Targets:

Power	EIRP	Scan Ratio	Frequency Range	Operating Range	Bandwidth	Response Time	Resolution	Dual Polarization
60 kW-1MW	30-70 dBmi	<20 sec/volume	2.3-2.5 Ghz (S), 9.4-9.6 Ghz (X)	500 km + (S), 70 km+ (X)	250-1000 MHz	Less than 150 picoseconds	0.2-1m (S), <5m (X)	Dual Polarization

ANNEX I Priority Use Case Market Segmentation

4.1 Defense and Intelligence

Market Segment	Annual Market	CAGR	Licensing NPV
Intelligence, Surveillance, and Reconnaissance (ISR)	\$7.3 billion	15%	\$3.3 billion
Electronic Warfare (EW)	\$16.6 billion	7%	\$3 billion
Navigation	\$18.7 billion	7%	\$3.4 billion
Platform Monitoring	\$11 billion	5%	\$2.7 billion
AI/Data Center Power/Thermal Management	\$19.6 billion	11-13%	3.3B

4.2 Energy and Utilities

Sector	Annual Market	CAGR	Licensing NPV
Solar Optimization	\$95 billion	17%	
Battery Storage	\$25 billion	9%	\$5.6 billion
Microgrids	\$11 billion	6%	\$1.8 billion
Small Modular Reactors (SMRs)	\$10 billion	8%	

CII NIKET North America LLC PROPRIETARY

4.3 Water and Environment

Product	Annual Market	CAGR	Licensing NPV
Desalination Membranes	\$20.6 billion	6%	\$3.3 billion
Real-Time Water Sensors	\$5 billion		

4.4 Healthcare and Biosecurity

Category	Annual Market
Biosensors	\$2.1 billion
Patient Monitoring	\$12 billion
Surgical Tools	\$8 billion

4.5 Transportation and Automotive

Category	Annual Market	CAGR	Licensing NPV
LIDAR/Radar	\$1.2 billion	42%	\$13.8 billion
Total Automotive Sensors	\$31 billion	5%	

ANNEX II Q-SMEC Strategic Positioning

- **Differentiators:** Key differentiating factors include quantum-level physics, AI-native research and development, export-compliant design, and an IP-only business model.
- **Trillion-Dollar Tailwinds:** The initiative benefits from significant market trends such as the energy transition, increasing autonomy, and defense modernization.
- **Weaknesses:** Identified weaknesses include the early Technology Readiness Level (TRL) and a broad scope.
- **Mitigation:** Initial commercialization efforts will be strategically focused on the Defense ISR/EW and Energy sectors to mitigate these weaknesses.

Economic Model

- Typical Use Case NRE project cost is \$770,000 over one year.
- Return on Investment (ROI) is contingent upon licensing velocity; three concurrent programs are projected to achieve break-even within one year with two Task 4 conversions.

CII NIKET North America LLC PROPRIETARY

Risk Register

Risk Categories, Challenges, and Mitigation Approaches

Category	Risk	Mitigation
Technical	Simulation–physical mismatch	Early physical test validation
Funding	Under-capitalized prototypes	Partner co-IP funding model
IP	Leakage of confidential material	NDA, data enclave, partial disclosure
Market	Dilution via over-broad claims	Prioritize two flagship sectors
Compliance	Export and cybersecurity gaps	ITAR/FedRAMP baseline built-in

ANNEX III Q-SMEC MATERIALS DESIGN MATRIX

Knob	Symbol	Range/Levels
Composition	x_i	10 disclosed + 11 confidential; 1–3 primaries + 0–2 dopants
Oxidation	n	–2...+5 depending on element
Dopant Fraction	c_d	10^{17} – 10^{21} cm ^{–3}
Layer Thickness	t_i	2 nm–2 μm per layer
Grain Size	d_g	5–200 nm
Pore Diameter (Membranes)	d_p	0.3–2.0 nm ($\sigma \leq 0.1$ nm)
Residual Stress	σ_r	≤ 200 MPa

Prototype Design — Geometries and Masks

Component	Details
EM Sensor Die	2×2 mm active area, interdigitated electrodes, guard ring, backside reflector for EO variants

CII NIKET North America LLC PROPRIETARY

Membrane Coupons	25 mm discs and 1812 cartridge format; stack 1–20 layers; epoxy-free edge seals for flux testing
------------------	--

Design for Manufacturability (DFM)/Design for Excellence (DFX) Details

DoD Project Management/Systems Engineering: phase-gate reviews system requirements review (SRR)/preliminary design review (PDR)/critical design review (CDR)/qualification review (QR)/test readiness review (TRR)/production readiness review (PRR); non-conformance report (NCR)/corrective and preventive action (CAPA) workflow

Risk and Probabilistic Assessment

Risk	P(occ)	Impact (\$)	Expected Loss	Mitigation
Simulation mismatch	0.35	400k	140k	Bench anchors, design-of-experiments reweight
Fabrication yield shortfall	0.30	300k	90k	SPC, recipe tuning, inline gates
Supply constraints	0.25	200k	50k	Dual-source, buffer inventory
Regulatory delay	0.20	250k	50k	Early audits, pre-briefs

AD 10272025